LTCC Bandpass Filter

BFCN-1052+

50Ω 9700 to 11950 MHz



The Big Deal

- Small size 3.2mm x 1.6mm
- Low loss in passband (1.5 dB typ over 9700 to 11950 MHz)
- Very high rejection over wide band

Product Overview

The BFCN-1052+ LTCC bandpass Filter achieves a miniature size and high repeatability of performance. Wrap-around terminations minimize variations in performance due to parasitics. Passing 9700-11950 MHz, these units offer excellent rejection over a wide stopband.

Key Features	Advantages
Small Size (3.20mm x1.6 mm)	Allows for high layout density of circuit boards, while minimizing effects of parasitics.
Rejection peaks close to pass band	Provides good rejection of signals close to the pass band, for improved system performance.
Wide stopband	Reduced regrowth at 2nd harmonic permits filter to be used in presence of wideband undesired signals.
LTCC construction	Provides a rugged package that is well suited for tough environments including high humidity and high temperature extremes.

Ceramic

Bandpass Filter

50Ω 9700 to 11950 MHz

Features

- Small size
- Temperature stable
- · Hermetically sealed
- LTCC construction

Applications

ATTENUATION (dB)

DC

- Harmonic Rejection
- Transmitters / Receivers

Specification Definition

F2 F4

• Test and Measurement

BFCN-1052+



Generic photo used for illustration purposes only

CASE STYLE: FV1206-9

+RoHS Compliant

The +Suffix identifies RoHS Compliance. See our web site for RoHS Compliance methodologies and qualifications



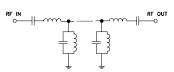
Electrical Specifications(1,2) at 25°C

Parai	neter	F#	Frequency (MHz)	Min.	Тур.	Max.	Unit	
	Center Frequency	_	_	_	10770	_	MHz	
Pass Band	Insertion Loss	F1-F2	9700-11950	_	1.6	3.0	dB	
	VSWR	F1-F2	9700-11950	_	1.9	_	:1	
Stop Band, Lower	Insertion Loss	DC-F3	DC-8100	30	38	_	dB	
	Insertion Loss		8100-8400	20	32	_	dB	
Stop Band, Upper	Insertion Loss	F4-F5	14000-28500	20	28	_	dB	
Stop Baild, Opper	Insertion Loss	F5-F6	28500-44000	_	25	_	dB	

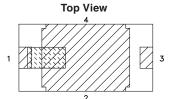
- 1. Measured on Mini-Circuits Characterization Test Board TB-1003+ with feedline losses removed by normalization of S12 and S21 traces to measurement of TB thru-line.
- This filter can not be used as a DC Blocking circuit element. In applications where DC voltage is present at either input or output ports, blocking capacitors are required at the corresponding RF port.

Functional Schematic

F3 F1



FREQUENCY (MHz)



Pad Connections

Input	1
Output	3
Ground	2

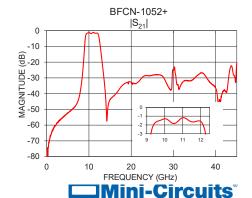
Maximum Ratings

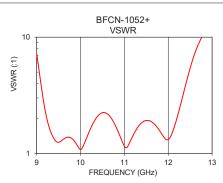
Operating Temperature	-55°C to +100°C
Storage Temperature	-55°C to +100°C
RF Power Input*	2W at 25°C

*Passband rating, derate linearly to 0.5W at 100°C ambient Permanent damage may occur if any of these limits are exceeded.

Typical Performance Data at 25°C

Frequency (GHz)	Insertion Loss (dB)	VSWR (:1)
1	-67.66	50.51
5	-53.39	26.26
8	-37.87	16.83
9	-12.22	7.04
10	-1.28	1.06
11	-1.38	1.63
12	-1.43	1.57
13	-13.21	5.03
15	-43.13	9.36
17	-37.34	11.85
20	-31.96	9.70
25	-28.59	6.41
35	-32.06	6.05
40	-40.15	5.17
41	-35.93	4.53



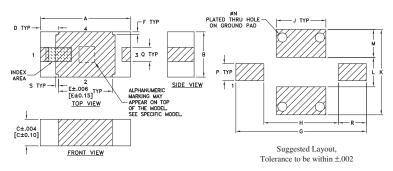


REV. OR ECO-000449 BFCN-1052+ BK/CP/AM 191025 Page 2 of 3

Bandpass Filter

BFCN-1052+

Outline Drawing



Pad Connections

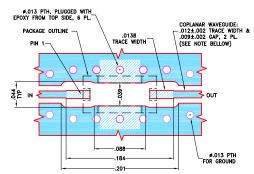
Input	1
Output	3
Ground	2

Product Marking: KL

Outline Dimensions (inch)

Α	В	С	D	Е	F	G	Н	J
.126	.063	.037	.026	.075	.004	.182	.104	.069
3.20	1.60	0.94	0.66	1.91	0.10	4.62	2.64	1.753
K	L	M	N	Р	Q	R	S	wt
	L 0.041			•			_	

Demo Board MCL P/N: TB-1003 + Suggested PCB Layout (PL- 610)



- NOIES:

 1. TRACE WIDTH AND GAP PARAMETERS ARE SHOWN FOR ROGERS RO4350B WITH DIELECTRIC THICKNESS. JOG6⁵²-LOOO7⁵. COPPER: 1/2 OZ. EACH SIDE. FOR OTHER MATERIALS TRACE WIDTH AND GAP MAY NEED TO BE MODIFIED.

 2. BOITOM SIDE OF THE PCB IS CONTINUOUS GROUND PLANE.

 3. UNIT LAND PATTERN WAS OPTIMIZED FOR BETTER PERFORMANCE.
- DENOTES PCB COPPER LAYOUT WITH SMOBC (SOLDER MASK OVER BARE COPPER). DENOTES COPPER LAND PATTERN FREE OF SOLDER MASK.

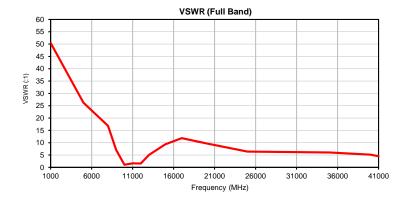
Additional Notes

- A. Performance and quality attributes and conditions not expressly stated in this specification document are intended to be excluded and do not form a part of this specification document.
- B. Electrical specifications and performance data contained in this specification document are based on Mini-Circuit's applicable established test performance criteria and measurement instructions.
- C. The parts covered by this specification document are subject to Mini-Circuits standard limited warranty and terms and conditions (collectively, "Standard Terms"); Purchasers of this part are entitled to the rights and benefits contained therein. For a full statement of the Standard Terms and the exclusive rights and remedies thereunder, please visit Mini-Circuits' website at www.minicircuits.com/MCLStore/terms.jsp



FREQUENCY	INSERTION LOSS	VSWR
(MHz)	(dB)	(:1)
1000	-67.66	50.51
5000	-53.39	26.26
8000	-37.87	16.83
9000	-12.22	7.04
10000	-1.28	1.06
11000	-1.38	1.63
12000	-1.43	1.57
13000	-13.21	5.03
15000	-43.13	9.36
17000	-37.34	11.85
20000	-31.96	9.70
25000	-28.59	6.41
35000	-32.06	6.05
40000	-40.15	5.17
41000	-35.93	4.53





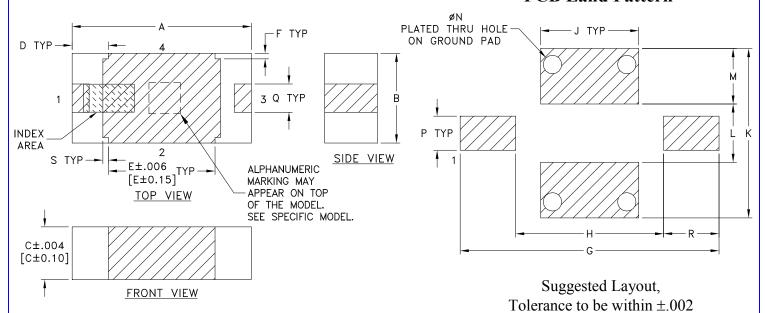
Case Style



FV1206-9

Outline Dimensions

PCB Land Pattern



CASE #	A	В	С	D	Е	F	G	Н	J	K	L	M
FV1206-9	.126	.063	.037	.026	.075	.004	.182	.104	.069	.119	.041	.039
	(3.20)	(1.60)	(0.94)	(0.66)	(1.91)	(0.10)	(4.62)	(2.64)	(1.75)	(3.02)	(1.04)	(0.99)

CASE#	N	P	Q	R	S	WT. GRAM
FV1206-9	.013 (0.33)	.024 (0.61)	.020 (0.51)	.039 (0.99)	.004 (0.10)	.020

Dimensions are in inches (mm). Tolerances: 2 Pl. ± .01; 3 Pl. ± .005

Notes:

- 1. Open style, ceramic base.
- 2. Termination finish: as shown below or indicated on Data Sheet.

For RoHS Case Styles: Tin plate over Nickel plate. All models, (+) suffix.

For RoHS-5 Case Styles: Tin-Lead plate. All models, no (+) suffix.



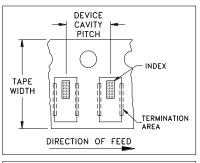


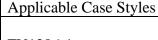
P.O. Box 350166, Brooklyn, New York 11235-0003 (718) 934-4500 Fax (718) 332-4661 For detailed performance specs & shopping online see Mini-Circuits web site The Design Engineers Search Engine Provides ACTUAL Data Instantly From MINI-CIRCUITS At: www.minicircuits.com

Tape & Reel Packaging

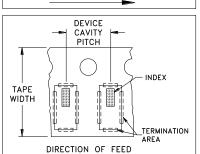
TR-F75

DEVICE ORIENTATION IN T&R

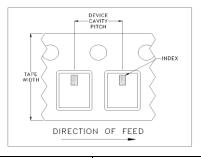




FV1206-1 FV1206-3



Applicable Case Styles
FV1206-4
FV1206-5
FV1206-6
FV1206-7
FV1206-9



Applicabl	e Case Styles
FV1206-1	12
GE0805C	C-18
NL1008C	2-6
NL1008C	2-7
NL1008C	:-9
NL1008C	C-10

ILLUSTRATION 3

ILLUSTRATION 1

ILLUSTRATION 2

Tape Width, mm	Device Cavity Pitch, mm	Reel Size, inches	Devices p	oer Reel
			Small	20
			quantity	50
			standards	100
8	4	7	(see note)	200
				500
				1000
			Standard	3000

Note: Please consult individual model data sheet to determine device per reel availability.

Mini-Circuits carrier tape materials provide protection from ESD (Electro-Static Discharge) during handling and transportation. Tapes are static dissipative and comply with industry standards EIA-481/EIA-541.

Go to: www.minicircuits.com/pages/pdfs/tape.pdf

Mini-Circuits ISO 9001 & ISO 14001 Certified



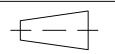
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P.O. Box 350166, Brooklyn, New York 11235-0003 (718) 934-4500 Fax (718) 332-4661

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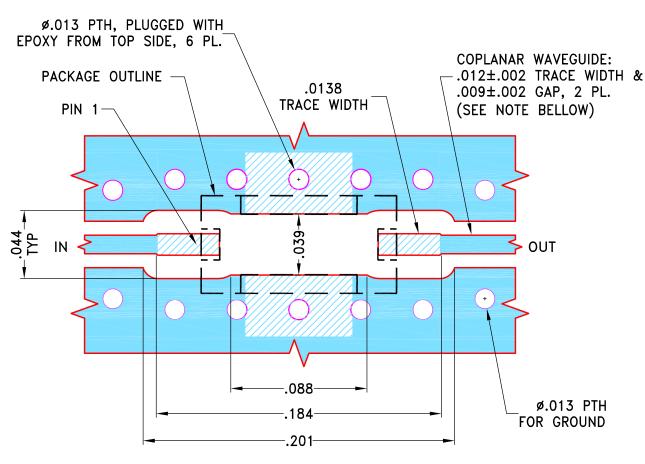
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THIRD ANGLE PROJECTION



		REVISIONS			
REV	ECN No.	DESCRIPTION	DATE	DR	AUTH
OR	M170506	NEW RELEASE	12/06/18	ITG	BK

SUGGESTED MOUNTING CONFIGURATION FOR FV1206-9 CASE STYLE, "04FL01" PIN CODE



NOTES:

- 1. TRACE WIDTH AND GAP PARAMETERS ARE SHOWN FOR ROGERS RO4350B WITH DIELECTRIC THICKNESS .0066"±.0007". COPPER: 1/2 OZ. EACH SIDE. FOR OTHER MATERIALS TRACE WIDTH AND GAP MAY NEED TO BE MODIFIED.
- 2. BOTTOM SIDE OF THE PCB IS CONTINUOUS GROUND PLANE.
- UNIT LAND PATTERN WAS OPTIMIZED FOR BETTER PERFORMANCE.

DENOTES PCB COPPER LAYOUT WITH SMOBC (SOLDER MASK OVER BARE COPPER). DENOTES COPPER LAND PATTERN FREE OF SOLDER MASK.

UNLESS OTHERWISE SPECIFIED		INITIALS	DATE	Г
DIMENSIONS ARE IN INCHES	DRAWN	ITG	12/05/18	
TOLERANCES ON: 2 PL DECIMALS ±	CHECKED	GF	12/05/18	
3 PL DECIMALS ± .005	APPROVED	BK	12/06/18	

ANGLES ± FRACTIONS ±

 \square Mini-Circuits ${\mathbb R}$

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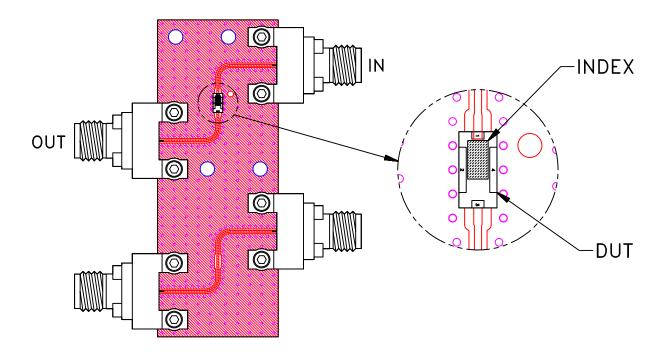
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]Mini-Circu	$\mathrm{itt}^{ exttt{@}}$	13 Neptune Avenue Brooklyn NY 11235
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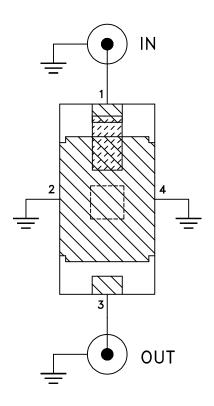
PL, 04FL01, FV1206-9, TB-1003+

	SIZE A	code ident 15542	DRAWING		-PL-61	0	REV:)R
_	FILE: 9	8PL610	SCALE:	16:1	SHEET:	1	OF :	1

Evaluation Board and Circuit



TB-1003+



Schematic Diagram

Notes:

- 1. 50 Ohm 2.92 mm Female connectors.
- 2. PCB Material: RO4350 or equivalent, Dielectric Constant=3.5, Thickness=.0066 inch.





Environmental Specifications

ENV06

All Mini-Circuits products are manufactured under exacting quality assurance and control standards, and are capable of meeting published specifications after being subjected to any or all of the following physical and environmental test.

Specification	Test/Inspection Condition	Reference/Spec	
Operating Temperature	-55° to 100°C Ambient Environment	Individual Model Data Sheet	
Storage Temperature	-55° to 100° C Ambient Environment	Individual Model Data Sheet	
Humidity	90 to 95% RH, 240 hours, 50°C	MIL-STD-202, Method 103, Condition A, Except 50°C and end-point electrical test done within 12 hours	
Solder Reflow Heat	Sn-Pb Eutetic Process: 225°C peak Pb-Free Process 245° - 250°C peak	J-STD-020, Table 4-1, 4-2 and 5-2, Figure 5-1	
Solderability	10X Magnification	J-STD-002, Para 4.2.5, Test S, 95% Coverage	
Vibration (High Frequency)	20g peak, 10-2000 Hz, 12 times in each of three perpendicular directions (total 36)	MIL-STD-202, Method 204, Condition D	
Mechanical Shock	50g, 11 ms, 1/2-sine, 18 shocks: 3 each direction, each of 3 axes	MIL-STD-202, Method 213, Condition A	

ENV06 Rev: A

02/25/11

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